

Preface

Testing and Failure Analysis are not only vital for ensuring long term reliability of the semiconductor products, but both components are critical for improved yields during production. Failure analysis works as a feedback mechanism and is an important step in the closed loop system of product manufacturing. Electrical testing, to ensure the quality of product is not good enough, but accurate signature analysis is an important component of failure analysis flow. The complexity of new semiconductor products with multiple layers of metals, complex packages such as BGA, CSP, flip chip and so on pose bigger problems for the failure analyst of the next millennium. ISTFA recognizes these needs of the failure analysts and thus present this unique forum for the analysts to gather and exchange their ideas and work. During this symposium the emphasis is on newer technologies which include papers on Microelectomechanical Systems (MEMS), a very fast emerging field which is poised to be a multi-billion dollar industry.

For a successful analysis, the failure analysts will be looking for proper signature analysis and a strategic plan as the two most vital components. The 23rd ISTFA presents an ideal opportunity for the engineers involved in Testing and Failure Analysis of the semiconductor devices. The three day symposium, and two day workshop along with an equipment exposition present an opportunity to the professions involved, to network, share, and learn from their colleagues.